

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGC180AP

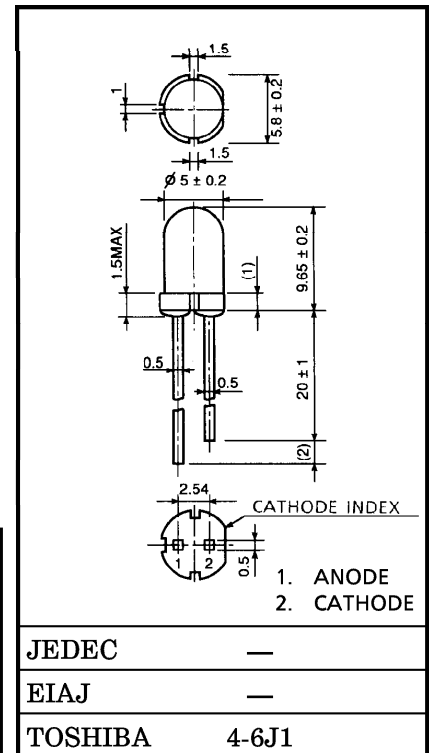
PANEL CIRCUIT INDICATOR

Unit in mm

- Striking Bright Green
- All Plastic Mold Type Colorless Clear Lens
- Low Drive Current, High Intensity Green Light Emission.
Recommended Forward Current : $I_F = 15 \sim 20 \text{mA}$ (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Without stand-offs

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

| CHARACTERISTIC | SYMBOL | RATING | UNIT |
|-----------------------------|-----------|---------|------|
| Forward Current (DC) | I_F | 40 | mA |
| Reverse Voltage | V_R | 4 | V |
| Power Dissipation | P_D | 120 | mW |
| Operating Temperature Range | T_{opr} | -20~85 | °C |
| Storage Temperature Range | T_{stg} | -30~100 | °C |



ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|---------------------------|-----------------|----------------------------|------|------|------|---------------|
| Forward Voltage | V_F | $I_F = 20\text{mA}$ | — | 2.15 | 2.8 | V |
| Reverse Current | I_R | $V_R = 4\text{V}$ | — | — | 5 | μA |
| Luminous Intensity | TLGC180AP | $I_F = 20\text{mA}$ (Note) | 85 | 300 | — | mcd |
| | TLGC180AP (NP) | | 85 | — | 414 | |
| | TLGC180AP (PQ) | | 153 | — | 736 | |
| Peak Emission Wave Length | λ_p | $I_F = 20\text{mA}$ | — | 567 | — | nm |
| Spectral Line Half Width | $\Delta\lambda$ | $I_F = 20\text{mA}$ | — | 25 | — | nm |

(Note) Rank selection carried out under next standard range respectively, although it needs $\pm 15\%$ additional for guaranteed limits.

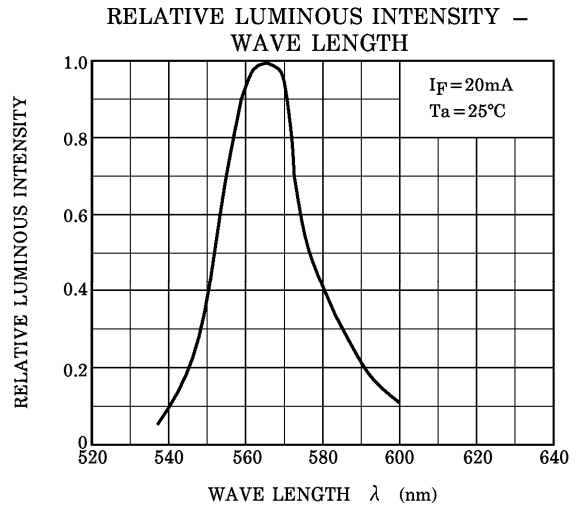
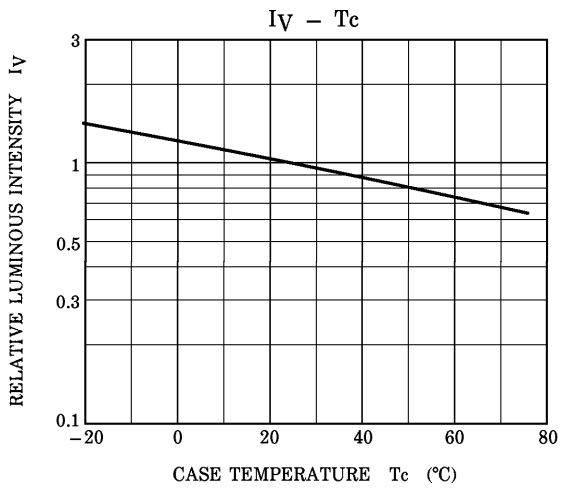
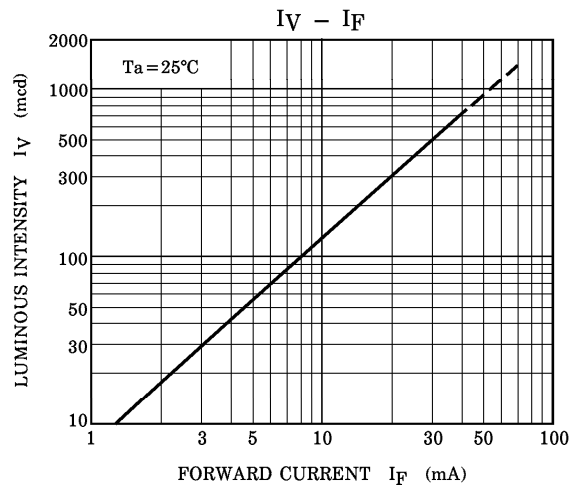
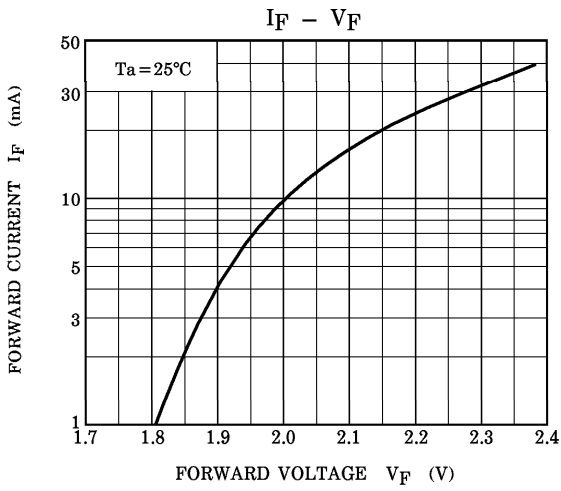
N : 100~200mcd P : 180~360mcd Q : 320~640mcd

Each rank products is classified by package unit, and (NP) includes N and P, (PQ) includes P and Q.

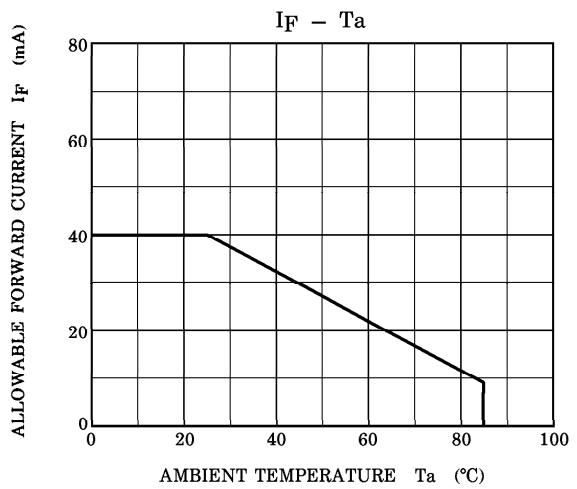
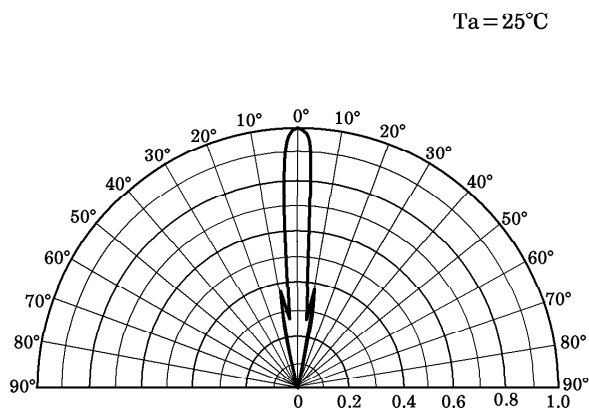
PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.



RADIATION PATTERN



RESTRICTIONS ON PRODUCT USE

000707EAA

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